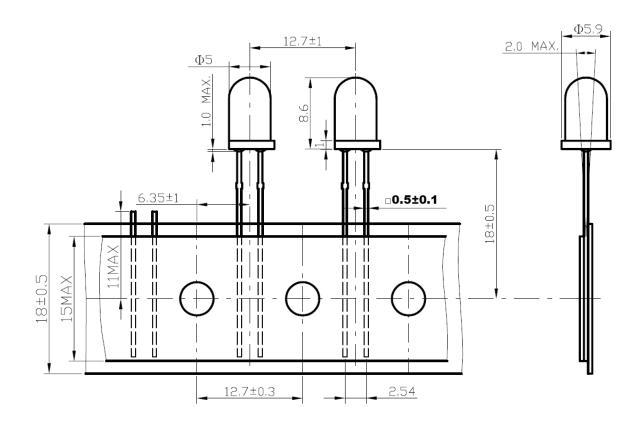


5mm Dia LED LAMP – Green Diffused

- ♦ 5.0mm DIA LED LAMP
- ♦ I.C. COMPATIBLE
- **♦ LOW POWER CONSUMPTION**

### **DIMENSIONS**



# **SELECTION GUIDE**

Chip Material	Chip Emitted	Lens Color	Viewing Angle	
GaP	GaP Green		60°	



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### **ABSOLUTE MAXIMUM RATINGS**

(Ta=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	$P_D$	65	mW
Pulse Forward Current (1/10 Duty Cycle @1KHz)	I <sub>PF</sub>	100	mA
Forward Current	I <sub>F</sub>	25	mA
Reverse Voltage	$V_R$	5.0	V
Operating Temperature Range	T <sub>OPR</sub>	-40~+85	°C
Storage Temperature Range	T <sub>STG</sub>	-40~+85	°C

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

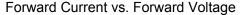
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	Iv	I <sub>F</sub> = 20mA	5	20		mcd
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA		2.05	2.6	V
Reverse Current	<b>I</b> R	V <sub>R</sub> = 5V			10	uA
Viewing Angle	201/2	I <sub>F</sub> = 20mA		60		deg.
Dominant Wavelength	λD	I <sub>F</sub> = 20mA		568	570	nm
Spectral line half-width	Δλ	I <sub>F</sub> = 20mA		30		Nm
Capacitance	С	V <sub>F</sub> = 0V, F= 1MHz		45		pF

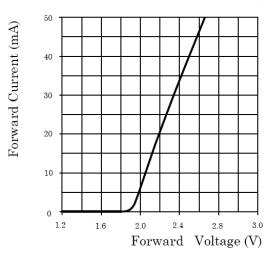


5mm Dia LED LAMP – Green Diffused

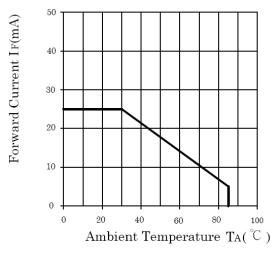
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### TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

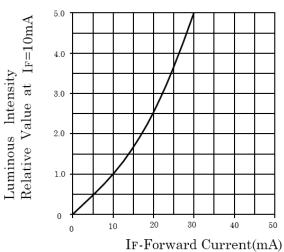




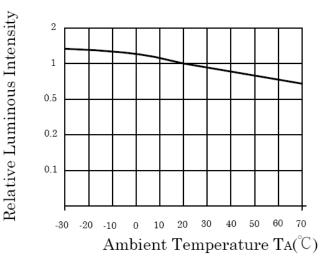
#### Forward Current vs. Temperature



#### Relative Intensity vs. Forward Current



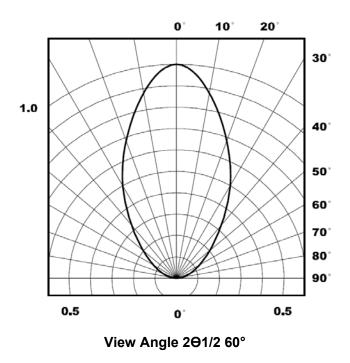
#### Relative Intensity vs. Temperature





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# **Wave Soldering**

SOLDERING INSTRUCTIONS						
TYPES	DIP AND WAVE SOLDERING			IRON SOLDERING(WITH 1.5mm IRON TIP)		
	TEMPERATURE OF THE SOLDERING BATH	MAXIMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE	TEMPERATURE OF SOLDERING IRON	MAXIMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE
LEDS	≦260°C	35	>2mm	≦295°C	35	>2mm
	≦ <b>260°C</b>	58	>4mm	≦ <b>295°C</b>	5\$	>4mm
DISPLAYS	≦ <b>260°C</b>	38	>2mm	≦ <b>295°C</b>	38	>2mm



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## LAMP HANDLING AND APPLICATION PRECAUTIONS

### **STORAGE**

(1.1) It is recommended to store the products in the following conditions:

Humidity: 60% RH Max.

Temperature:  $5^{\circ}\text{C} \sim 40^{\circ}\text{C}(41^{\circ}\text{F} \sim 105^{\circ}\text{F})$ 

(1.2) Shelf life in sealed bag: 3 month at  $< 40^{\circ}$ C and < 90% RH.

#### **FORMING**

- 1. Any forming on lead pin must be done before soldering, not during or after soldering.
- 2. Avoid applying any stress to resin in order to prevent the epoxy fracture and break on bonding wire.
- 3. While forming, please use a tie bar cut or equivalent to hold or bend the pin.
- 4. 2mm from the base of resin is the minimum distance for the place bending the lead pin.
- 5. Avoid bending the lead pin at the same point twice or more.

### **SOLDERING**

- 1. No stress can be applied to lead pins when they are heated, otherwise disconnection may occur.
- 2. When an LED is mounted into a P.C. board, pitch spacing should be aligned carefully to avoid causing any stress to the lead wires.
- 3. Mounting direction ( electrode direction ) of SMD LED and Display should be perpendicular to direction of p.c. board curve.
- 4. After soldering, don't bend the P.C. board.

## **CLEANING**

- 1. Avoid using any unspecified chemical solvent to clean LED. For example, Trichoroethylene, Chlorosen, Acetone, and Diflon S3MC.
- 2. Any cleaning method can only be taken under normal temperature in one minute or less if it is required.
- 3. Special attention should be taken when using any chemicals for cleaning because some chemicals may damage the surface of epoxy.